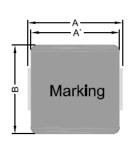
1. Part No. Expression:

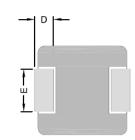
PICQ 1206 HP R 47 M F

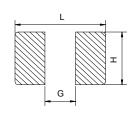
- (a)
- (b)
- (C
 - (c) (d) (e)(f)
- \/**f**\
- a) Series Code
- e) Tolerance Codef) RoHS Compliant
- b) Dimension Code
- c) Type Code
- d) Inductance Code

2. Configuration & Dimensions:

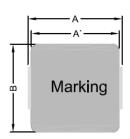




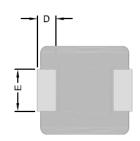




Recommended PC Board Pattern







non-Leadframe

Note:

- 1. The above PCB layout is for reference only.
- 2. Solder paste thickness of 0.15mm and above is recommended.
- 3. Marking: Top row Inductance code, Bottom row Year/World week

Unit: mm

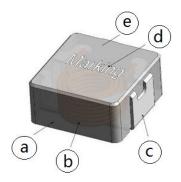
Series	Туре	Α	A`	В	С	D	E	L	G	Н
PICQ1206	Leadframe	12.5.0.5	12.5±0.3	12.5±0.3	5.7±0.3	2.3±0.3	4.7±0.3	14.2 Ref.	8.0 Ref.	5.0 Ref.
	Non-Leadframe	13.5±0.5								

3. Schematic:



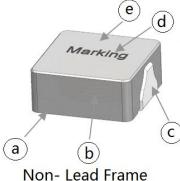


4. Material List:



Lead Frame

- a) Core
- b) Wire
- c) Clip
- d) Ink
- e) Paint



- a) Core
- b) Wire
- c) Solder
- d) Ink
- e) Paint

5. General Specification:

Reliability test for this part meets AEC-Q200 standard (a)

(b) Operating Temp.: -55°C to +125°C(including self-temperature rise)

(c) Storage Temp.: -55°C to +125°C (on board)

(d) Humidity Range.: 85 ± 3% RH

Heat Rated Current (Irms) will cause the coil temperature rise approximately Δt of 40°C (e)

(f) Saturation Current (Isat Typ.) will cause L0 to drop approximately 30%

Part Temperature (Ambient+Temp. Rise): Should not exceed 125°C under worst case operating conditions. (g)

(h) Storage condition (component in its packaging)

i) Temperature: Less than 40°C

ii) Humidity: 60% RH



6. Electrical Characteristics:

Part Number	Inductance L0 (uH) @ 0 A	Test Frequency, L	I rms (A) Typ.	I sat (A) Typ.	DCR(mΩ) Typ.@25°C	DCR(mΩ) Max.@25°C	Туре
PICQ1206HPR47MF	0.47	100KHz/1.0V	38.0	64.0	0.92	1.3	Non-Leadframe
PICQ1206HPR56MF	0.56	100KHz/1.0V	35.0	60.0	1.15	1.5	Non-Leadframe
PICQ1206HPR68MF	0.68	100KHz/1.0V	33.0	57.0	1.33	1.7	Non-Leadframe
PICQ1206HP1R0MF	1.00	100KHz/1.0V	29.0	53.0	1.8	2.4	Non-Leadframe
PICQ1206HP1R2MF	1.20	100KHz/1.0V	28.0	51.0	2.1	2.8	Non-Leadframe
PICQ1206HP1R5MF	1.50	100KHz/1.0V	26.0	50.0	2.7	3.2	Non-Leadframe
PICQ1206HP2R2MF	2.20	100KHz/1.0V	21.0	43.0	4.0	4.7	Leadframe
PICQ1206HP2R7MF	2.70	100KHz/1.0V	19.0	40.0	4.6	5.4	Leadframe
PICQ1206HP3R3MF	3.30	100KHz/1.0V	17.0	35.0	5.8	7.1	Leadframe
PICQ1206HP4R7MF	4.70	100KHz/1.0V	16.0	30.0	9.5	11.5	Leadframe
PICQ1206HP5R6MF	5.60	100KHz/1.0V	15.5	28.0	10.8	12.6	Leadframe
PICQ1206HP6R8MF	6.80	100KHz/1.0V	15.0	25.0	12.0	13.8	Leadframe
PICQ1206HP8R2MF	8.20	100KHz/1.0V	11.0	23.0	13.6	16.0	Leadframe
PICQ1206HP100MF	10.0	100KHz/1.0V	11.0	21.0	18.0	20.7	Leadframe
PICQ1206HP120MF	12.0	100KHz/1.0V	9.5	18.0	20.0	23.0	Leadframe
PICQ1206HP150MF	15.0	100KHz/1.0V	9.0	16.0	25.0	29.0	Leadframe
PICQ1206HP180MF	18.0	100KHz/1.0V	8.5	15.0	30.0	35.0	Leadframe
PICQ1206HP220MF	22.0	100KHz/1.0V	8.0	14.0	34.0	39.5	Leadframe
PICQ1206HP270MF	27.0	100KHz/1.0V	7.0	13.0	49.0	56.0	Leadframe
PICQ1206HP330MF	33.0	100KHz/1.0V	6.0	12.0	65.0	75.0	Leadframe
PICQ1206HP470MF	47.0	100KHz/1.0V	5.5	11.0	80.0	90.0	Leadframe
PICQ1206HP560MF	56.0	100KHz/1.0V	5.3	10.0	101	118	Leadframe
PICQ1206HP680MF	68.0	100KHz/1.0V	5.0	9.0	120	140	Leadframe
PICQ1206HP820MF	82.0	100KHz/1.0V	4.5	8.5	138	161	Leadframe
PICQ1206HP101MF	100	100KHz/1.0V	4.0	8.0	180	200	Leadframe
PICQ1206HP121MF	120	100KHz/1.0V	3.5	7.0	210	235	Leadframe
PICQ1206HP151MF	150	100KHz/1.0V	3.0	6.0	300	350	Leadframe

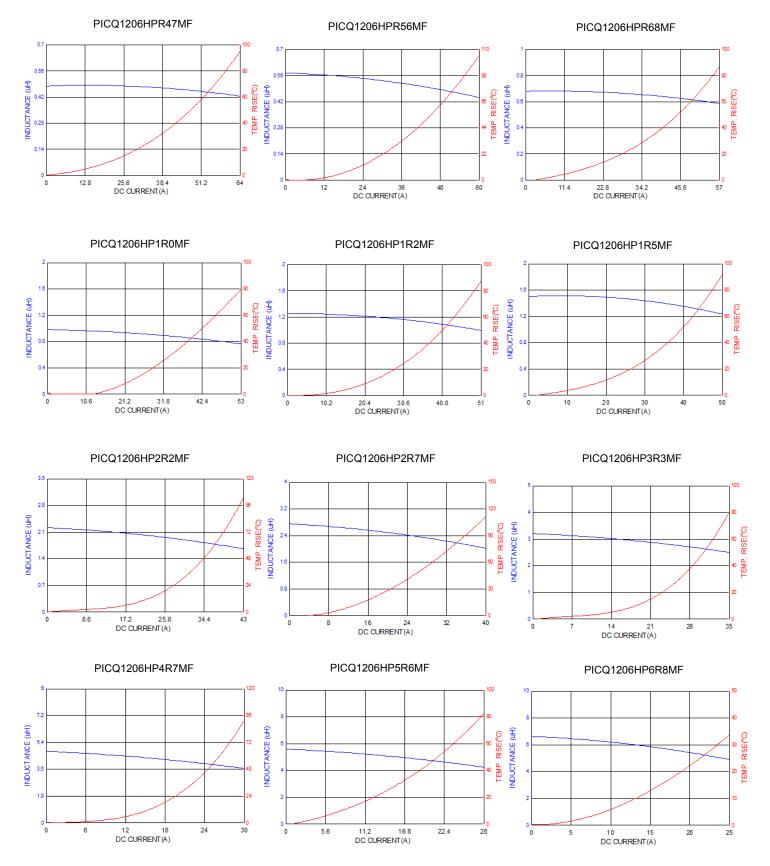
*Tolerance code : Y = $\pm 30\%$; M = $\pm 20\%$

Notes:

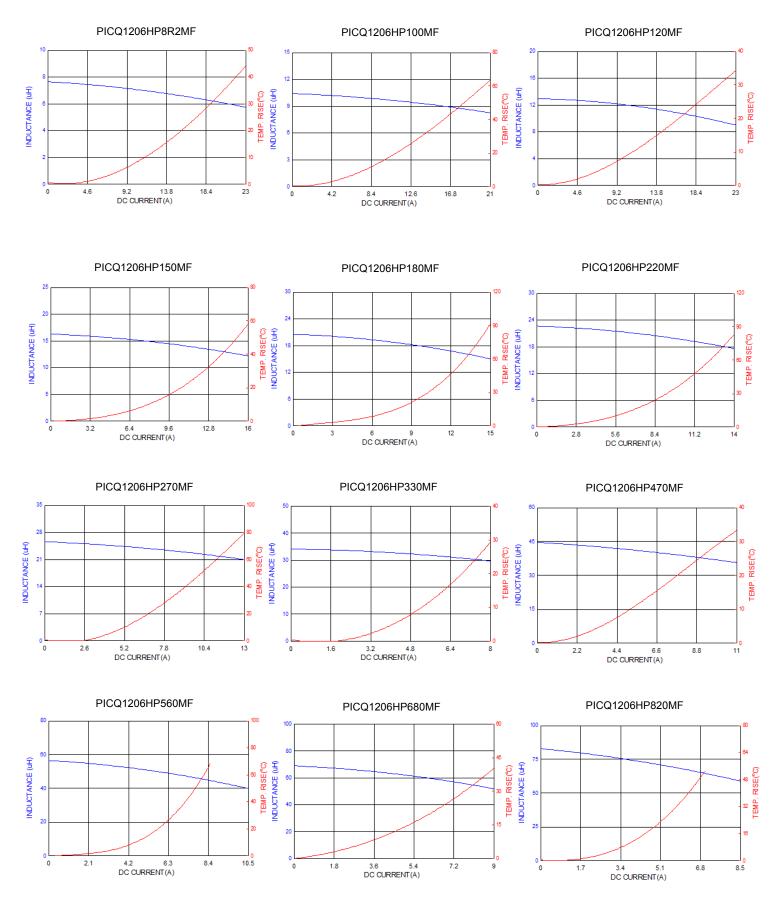
1) Isat Typ. and Irms Typ. value is derived based from accounting the upper limit tolerance into the inductance value.



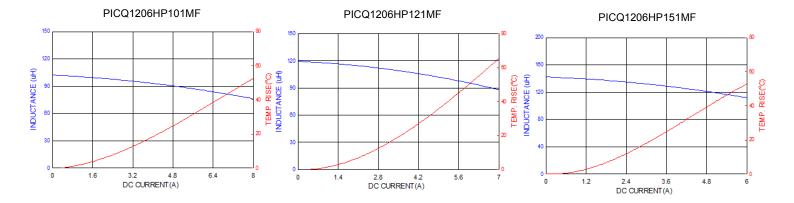
7. Characteristics Curves:













8. Soldering:

Mildly activated rosin fluxes are preferred. The minimum amount of solder can lead to damage from the stresses caused by the difference in coefficients of expansion between solder, chip and substrate. Our terminations are suitable for all re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air.

8-1 Solder Re-flow:

Recommended temperature profiles for re-flow soldering in Figure 1.

8-2 Soldering Iron (Figure 2):

Products attachment with soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended.

Note:

- a) Preheat circuit and products to 150°C.
- b) 355°C tip temperature (Max.)
- c) Never contact the ceramic with the iron tip
- d) 1.0mm tip diameter (Max.)
- e) Use a 20 watt soldering iron with tip diameter of 1.0mm
- f) Limit soldering time to 4~5 secs.

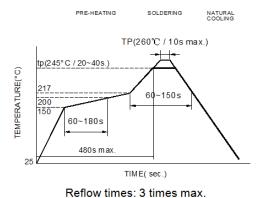
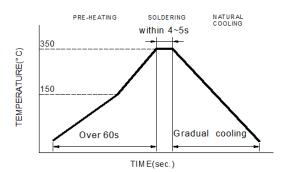


Fig.1

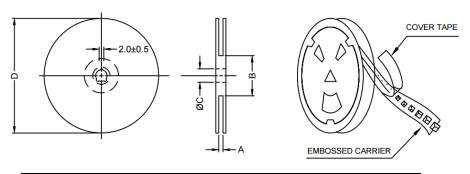


Iron Soldering times: 1 times max.

Fig.2

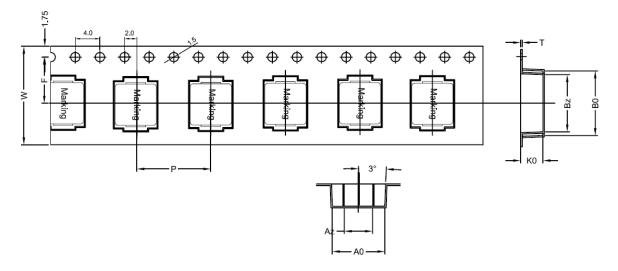
9. Packaging Information:

9-1 Reel Dimension



Туре	A(mm)	B(mm)	C(mm)	D(mm)	
13"x24mm	24.4+2/-0	100±2	13.0+0.5/-0.2	330	

9-2 Tape Dimension

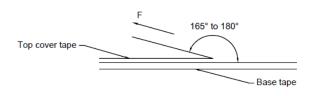


Series	Size	Bo(mm)	Bz(mm)	Ao(mm)	Az(mm)	Ko(mm)	P(mm)	W(mm)	F(mm)	t(mm)
PICQ	1206	14.1±0.1	13.0±0.1	12.9±0.1	7.0±0.1	6.5±0.1	16.0±0.1	24±0.3	11.5±0.1	0.35±0.05

9-3 Packaging Quantity

PICQ	1206		
Chip / Reel	500		
Inner box	1,000		
Carton	4,000		

9-4 Tearing Off Force



The force for tearing off cover tape is 10 to 130 grams in the arrow direction under the following conditions

Room Temp. (°C)	Room Humidity (%)	Room atm (hPa)	Tearing Speed mm/min	
5~35	45~85	860~1060	300	

Application Notice:

1. Storage Conditions:

To maintain the solderability of terminal electrodes:

- a) Recommended products should be used within 12 months from the time of delivery.
- b) The packaging material should be kept where no chlorine or sulfur exists in the air.

2. Transportation:

- a) Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- b) Vacuum pick up is strongly recommended for individual components.
- c) Bulk handling should ensure that abrasion and mechanical shock are minimized.